CHIPQUIK® CQ4LF-2S

Datasheet revision 1.2 www.chipquik.com

Liquid Flux No-Clean in 60ml (2oz) Spray Bottle



Product Highlights

A liquid flux that is non-flammable
No-Clean
Water-Based, leaves no residues
VOC Free, Halide Free, Rosin Free
Ideal for all rework, solder, and de-solder applications
Excellent wetting
Easily cleaned with isopropyl alcohol (IPA)
Can be used with Leaded and Lead-Free applications
RoHS 3 and REACH compliant

Specifications

Flux Type:	No-Clean Liquid Flux (for Leaded and Lead-Free applications)
Flux Classification:	ORL0
VOC Content:	VOC Free
Acid Number:	38.0
Total Solids:	4.0%
Specific Gravity:	1.01
Packaging:	60ml (2oz) Spray Bottle
Shelf Life:	Refrigerated >24 months, Unrefrigerated >24 months

Storage and Handling

Store refrigerated or at room temperature 3-25°C (37-77°F). The liquid flux can be allowed to freeze. Freezing will not degrade this product. Allow 4 hours for flux to reach an operating temperature of 20-25°C (68-77°F) before use.

Transportation

This product has no shipping restrictions. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground or air will not impact this product's stated shelf life.

Cleaning

This is a no-clean liquid flux, post-use cleaning is not required.

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Test Results

Test J-STD-004 or other requirements as stated	Test Requirement	Result
Copper Mirror	IPC-TM-650: 2.3.32	L: No breakthrough
Corrosion	IPC-TM-650: 2.6.15	L: No corrosion
Quantitative Halides	IPC-TM-650: 2.3.28.1	L: <0.05%
Electrochemical Migration	IPC-TM-650: 2.6.14.1	L: <1 decade drop (No-clean)
Surface Insulation Resistance 85°C, 85% RH @ 168 Hours	IPC-TM-650: 2.6.3.7	L: ≥100MΩ (No-clean)
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials

Conforms to the following Industry Standards:

J-STD-004B, Amendment 1 (Solder Fluxes):	Yes
RoHS 3 Directive (EU) 2015/863:	Yes

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